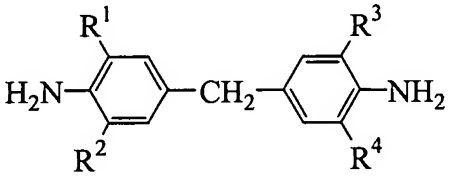
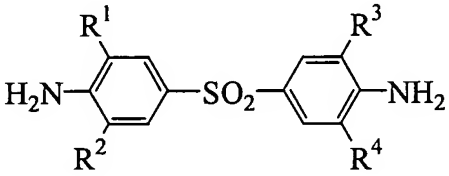
AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A liquid epoxy resin composition comprising (A) a liquid epoxy resin, (B) an aromatic amine curing agent, and (C) an inorganic filler, wherein

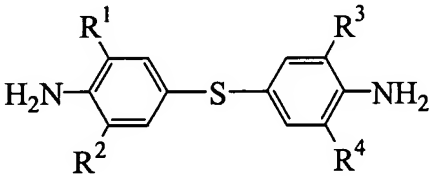
the aromatic amine curing agent (B) comprises at least 5% by weight based on the entire curing agent of at least one aromatic amine compound having a purity of at least 99% selected from compounds having the following general formulae (1) to (3):



(1)



(2)



(3)

wherein each of R^1 to R^4 is hydrogen or a monovalent hydrocarbon group having 1 to 6 carbon atoms,

the liquid epoxy resin (A) and the aromatic amine curing agent (B) are present in a molar ratio (A)/(B) from 0.7/1 to less than 0.9/1, and

the composition has a toughness K_{1c} of at least 3.5, and is substantially free of an alkoxy-bearing silane coupling agent except that an alkoxy-bearing silane coupling agent is used for the surface treatment of the inorganic filler.

2. (Canceled)

3. (Withdrawn) The composition of claim 1, further comprising a silicone-modified resin in the form of a copolymer which is obtained from an alkenyl group-containing epoxy resin or phenolic resin and an organopolysiloxane having the average compositional formula (4):

$$H_aR^5_bSiO_{(4-a-b)/2} \qquad (4)$$

wherein R^5 is a substituted or unsubstituted monovalent hydrocarbon group, "a" is a number of 0.01 to 0.1, "b" is a number of 1.8 to 2.2, and $1.81 \leq a+b \leq 2.3$, said organopolysiloxane containing per molecule 20 to 400 silicon atoms and 1 to 5 hydrogen atoms each directly attached to a silicon atom (i.e., SiH groups), by effecting addition reaction between alkenyl groups and SiH groups.

4. (Withdrawn) A semiconductor device which is encapsulated with the liquid epoxy resin composition of claim 1 in the cured state.

5. (Withdrawn) A flip chip type semiconductor device which is encapsulated with the liquid epoxy resin composition of claim 1 in the cured state as an underfill.

6. (New) The composition of claim 1, wherein the liquid epoxy resin (A) and the aromatic amine curing agent (B) are present in a molar ratio (A)/(B) from 0.7/1 to 0.85/1.

7. (New) The composition of claim 1, wherein the composition has a toughness K_{1c} of at least 4.0.

8. (New) The composition of claim 1, wherein the inorganic filler is spherical silica.